

1 Claim 26. An electronic package comprising:  
2 a first circuitized substrate having at least one conductive aperture therein having  
3 an external surface;  
4 a second circuitized substrate having at least one conductive aperture therein  
5 having an external surface, said first and second circuitized substrates aligned such that  
6 said at least one conductive aperture of said first circuitized substrate is substantially  
7 aligned with said at least one conductive aperture of said second circuitized substrate, said  
8 at least one conductive aperture of said first circuitized substrate and said at least one  
9 conductive aperture of said second circuitized substrate including a conductive metallic  
10 layer thereon selected from the group consisting of copper, nickel, gold, chromium, solder  
11 and alloys thereof; and  
12 at least one solder member including a first contact portion extending from said  
13 external surface of said conductive aperture of said first circuitized substrate, said first  
14 contact portion including a cross-sectional configuration that is substantially round, oval  
15 or ellipsoidal, and a second contact portion extending substantially within both of said  
16 aligned conductive apertures of said first and second circuitized substrates to at least said  
17 external surface of said conductive aperture of said second circuitized substrate to secure  
18 said circuitized substrates together.

1 Claim 28. The electronic package of Claim 26 wherein said conductive metallic  
2 layer is copper including a protective layer thereon, said protective layer selected from the  
3 group consisting of benzotriazole, chlorite, and immersion tin.